

S-Band 60W GaN High Power Amplifier

GaN HEMT on SiC and GaAs Monolithic Microwave Matching Circuits in SMD leadless package

Description

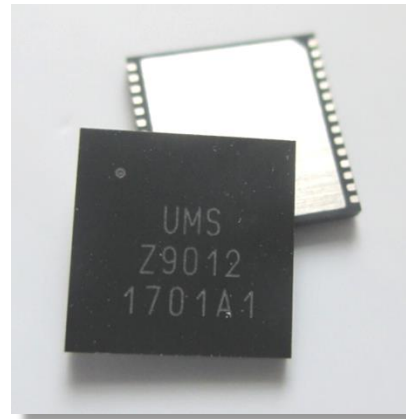
The CHZ9012-QFA is an S-Band Quasi-MMIC High Power Amplifier based on GaN power bar and GaAs input and output matching circuits.

It is fabricated using UMS 0.25µm GaN on SiC and GaAs MMIC High Power UMS Passive technologies.

The CHZ9012-QFA is fully matched on 50 Ohms. It can be used following several operating conditions to meet system requirements. This product is dedicated to a wide range of applications, from military to commercial radar systems.

The CHZ9012-QFA is proposed in low cost plastic package providing low parasitic and low thermal resistance.

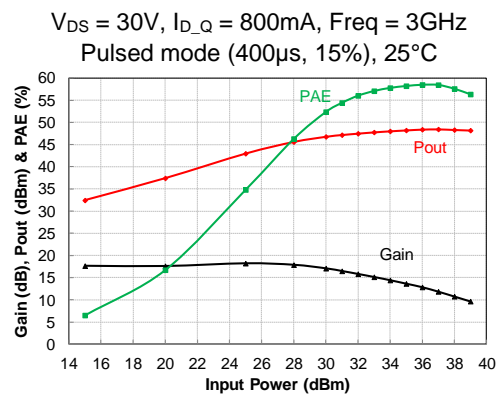
The CHZ9012-QFA is supplied in RoHS compliant SMD package.



30 leads DFN package-8x8 mm²

Main Features

- Frequency Range: 2.7-3.4GHz
- Pulsed operating mode
- High power: > 60W
- High Efficiency: > 50%
- DC bias: Vd up to 30Volt
- Low cost package: 30L-DFN 8x8mm²
- Compatible UMS Driver: CHZ8012-QJA



Performances on S-band Evaluation Board

Main Electrical Characteristics

T_{case}= +25°C, Pulsed mode, V_{DS}=30V, I_{D-Q}=800mA

| Symbol | Parameter | Min | Typ | Max | Unit |
|--------|----------------------------|-----|-----|-----|------|
| Freq | Frequency range | 2.7 | | 3.4 | GHz |
| Gain | Linear Gain | | 16 | | dB |
| Pout | Saturated Output Power | | 65 | | W |
| PAE | Max Power Added Efficiency | | 52 | | % |

Recommended Operating Ratings

$T_{case} = +25^{\circ}C$

| Symbol | Parameter | Min | Typ | Max | Unit | Conditions |
|--------------|------------------------------|-----|------|--------------------|-------------|-----------------------------------|
| V_{DS} | Drain to Source Voltage | | | 30 | V | |
| V_{GS} | Gate to Source Voltage | | -3.7 | | V | $V_{DS}=30V$, $I_{D_Q}=0.8A$ |
| I_{D_Q} | Quiescent Drain Current | | 0.8 | 1.1 ⁽¹⁾ | A | $V_{DS} =30V$ |
| I_{D_MAX} | Drain Current | | 4 | (1) | A | $V_{DS}=30V$, compressed mode |
| I_{G_MAX} | Gate Current in forward mode | | 0 | 80 | mA | DC or Compressed mode |
| Pw | Pulse width | | 0.4 | 1 | ms | Pulse width |
| DC | Duty Cycle | | 10 | 15 | % | Duty Cycle |
| T_{case} | Case Operating Temperature | -30 | | 100 | $^{\circ}C$ | (1) |
| T_{j_MAX} | Junction temperature | | | 200 | $^{\circ}C$ | (1) |

(1) Power dissipation must be considered.

Electrical Characteristics

$T_{case} = +25^{\circ}C$, RF Pulsed mode (400 μ s / 15%), Class AB ($I_{D_Q}=800mA$)

| Symbol | Parameter | Min | Typ | Max | Unit |
|----------------|--------------------------------|-----|------|-----|------|
| Fop | Operating frequency range | 2.7 | | 3.4 | GHz |
| Gain | Small Signal Gain | | 15 | | dB |
| P_{sat} | Saturated Output Power | | 48 | | dBm |
| PAE | Power Added Efficiency | | 55 | | % |
| G_{PAE_max} | Associated gain at maximum PAE | | 12 | | |
| V_{DS} | Biasing Drain Voltage | | 30 | | V |
| V_{GS} | Biasing Gate Voltage | | -3.7 | | V |
| I_{D_Q} | Quiescent drain current | | 800 | | mA |
| RI_{in} | Input Return Loss | | -11 | | dB |
| RI_{out} | Output Return Loss | | -6.5 | | dB |

These values are representative of on board measurements as defined on the drawing in paragraph "Evaluation Board".

Electrical Characteristics

$T_{case} = +25^{\circ}\text{C}$, RF Pulsed mode (400 μs / 15%), Class B ($I_{D_Q} \sim 0\text{mA}$)

| Symbol | Parameter | Min | Typ | Max | Unit |
|----------------------|---------------------------------|-----|------|-----|------|
| F _{op} | Operating frequency range | 2.8 | | 3.4 | GHz |
| P _{sat} | Saturated Output Power | | 48 | | dBm |
| PAE | Power Added Efficiency | | 55 | | % |
| G _{PAE_max} | Associated gain at maximum PAE | | 10 | | |
| V _{DS} | Biassing Drain Voltage | | 30 | | V |
| V _{GS} | Biassing Gate Voltage | | -4,8 | | V |
| RI _{in} | Input Return Loss @ maximum PAE | | -11 | | dB |

These values are representative of on board measurements as defined on the drawing in paragraph "Evaluation Board".

Absolute Maximum Ratings ⁽¹⁾ ⁽²⁾ ⁽³⁾

| Symbol | Parameter | Rating | Unit | Note |
|--------------------|---|-------------|------|---------|
| V _{DS} | Drain-Source Biassing Voltage | -0.5, +35 | V | |
| V _{GS_Q} | Gate-Source Biassing Voltage | -15, -1 | V | (4) (5) |
| I _{G_MAX} | Maximum Gate Current (forward mode; 25°C) | 175 | mA | (4) |
| I _{G_MIN} | Minimum Gate Current (reverse mode; 25°C) | -11 | mA | |
| P _{IN} | Maximum Input Power | 42 | dBm | (4) (5) |
| P _w | Pulse width | 3 | ms | (4) |
| DC | Duty Cycle | 30 | % | (4) |
| T _j | Junction temperature | 230 | °C | |
| T _{STG} | Storage Temperature | -55 to +125 | °C | |
| T _{Case} | Case Operating Temperature | -40 to +110 | °C | (4) |

⁽¹⁾ Operation of this device above anyone of these parameters may cause permanent damage.

⁽²⁾ Duration < 1s.

⁽³⁾ The given values must not be exceeded at the same time even momentarily for any parameter, since each parameter is independent from each other. Otherwise deterioration or destruction of the device may take place.

⁽⁴⁾ Max junction temperature must be considered

⁽⁵⁾ Limited by I_{G_MAX} & I_{G_MIN} values.

Biassing procedure

1. Bias power bar gate voltage at V_{GS} close to V_{pinch-off} (Typically: V_{GS} ≈ -5V)
2. Apply V_{DS} bias voltage (Typically: V_{DS} = 30V)
3. Increase V_{GS} up to quiescent bias drain current I_{D_Q}

The quiescent current steady state must be carefully controlled as it is influenced by the operating mode, the temperature and the overall thermal resistance.

A drain current control is recommended on the biassing network.

Device thermal performances

The thermal performances of the device are based on UMS rules to evaluate the junction temperature (T_j). This temperature is defined as the peak temperature in the channel area.

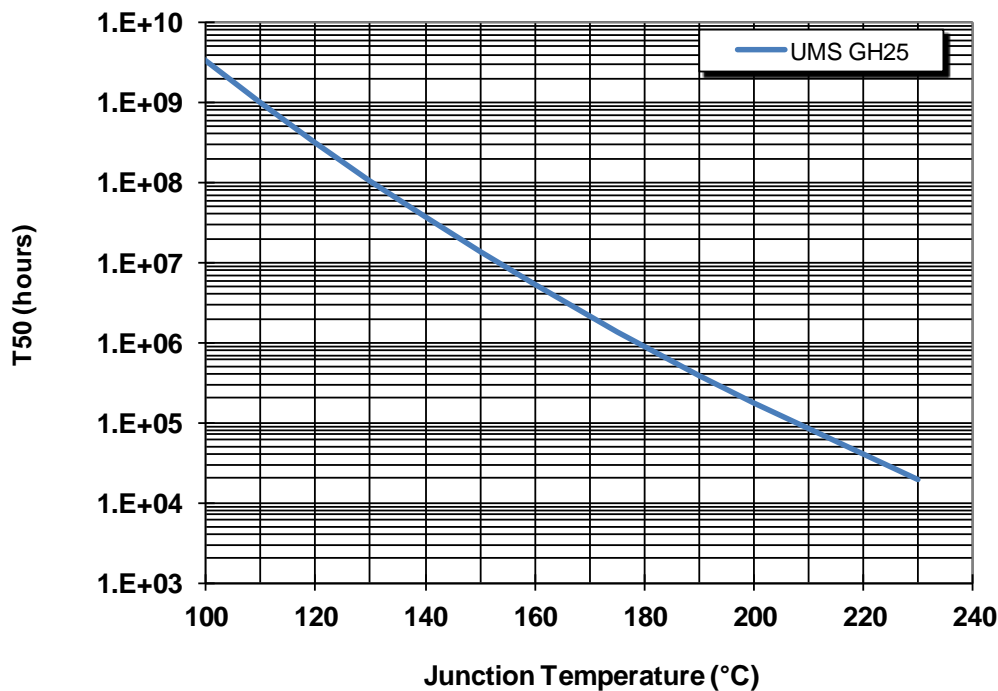
This same procedure is the basis for junction temperature evaluation of the samples used to derive the Median lifetime and activation energy for the particular technology on which the CHZ9012-QFA is fabricated (GaN Power PHEMT 0.25 μ m).

The temperature T_{case} is defined as the package back side temperature.

The thermal resistance (R_{th}) is considered in pulsed mode as given in the table. The device assembly must be adapted to the operating mode, especially for SMD components which are very dependent on PCB characteristics. Thermal analysis is recommended. More information is available on request.

| Parameters | Symbol | Conditions (Package) | Value | Unit |
|--|----------|--|-------------------------|---------------|
| Typical Thermal Resistance (junction-case) | R_{th} | $T_{case} = 95^{\circ}C$ $P_{in}=39dBm$ Total dissipated power=50W | 0.86 (global device) | $^{\circ}C/W$ |
| Junction Temperature | T_j | (Saturated operating mode) Pulsed mode: 400 μ s/15% | 138 | $^{\circ}C$ |

Median Life Time versus Junction Temperature



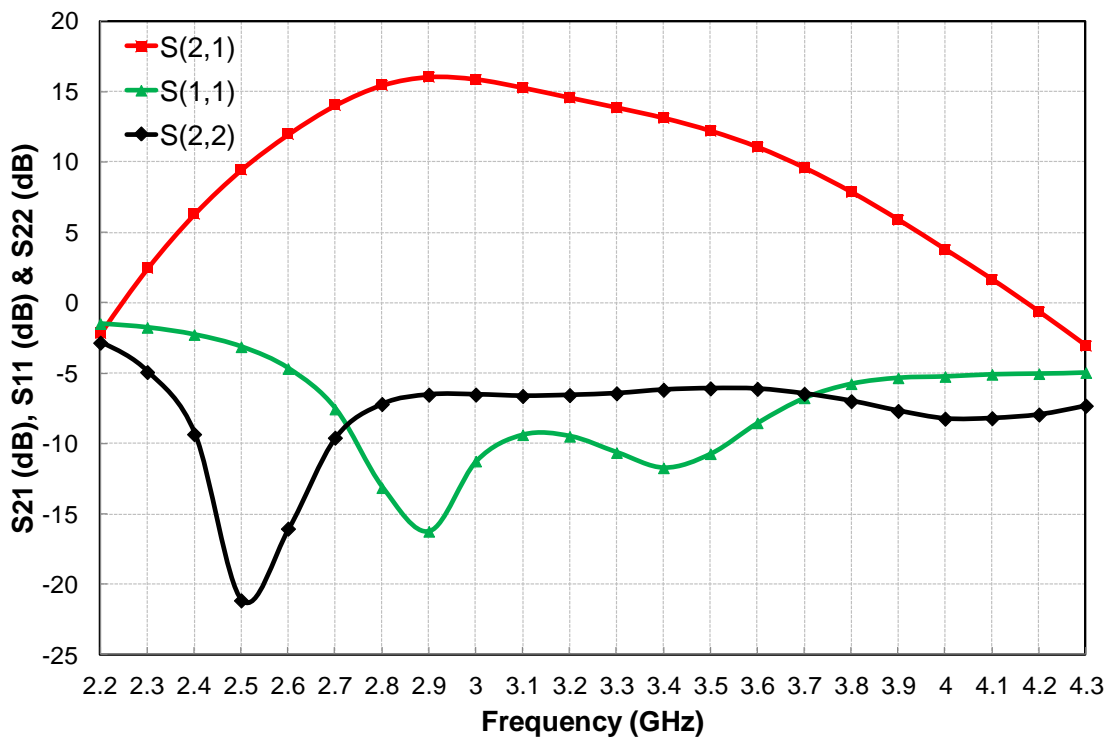
Typical S-parameters Measurements

Calibration and measurements are done on the connector reference accesses of the demonstration boards.

$T_{case} = +25^{\circ}C$, $V_{DS}=30V$, $I_{D,Q}=800mA$.

Pulsed input power : 400 μ s / 15%

S21, S11 & S22 versus Frequency

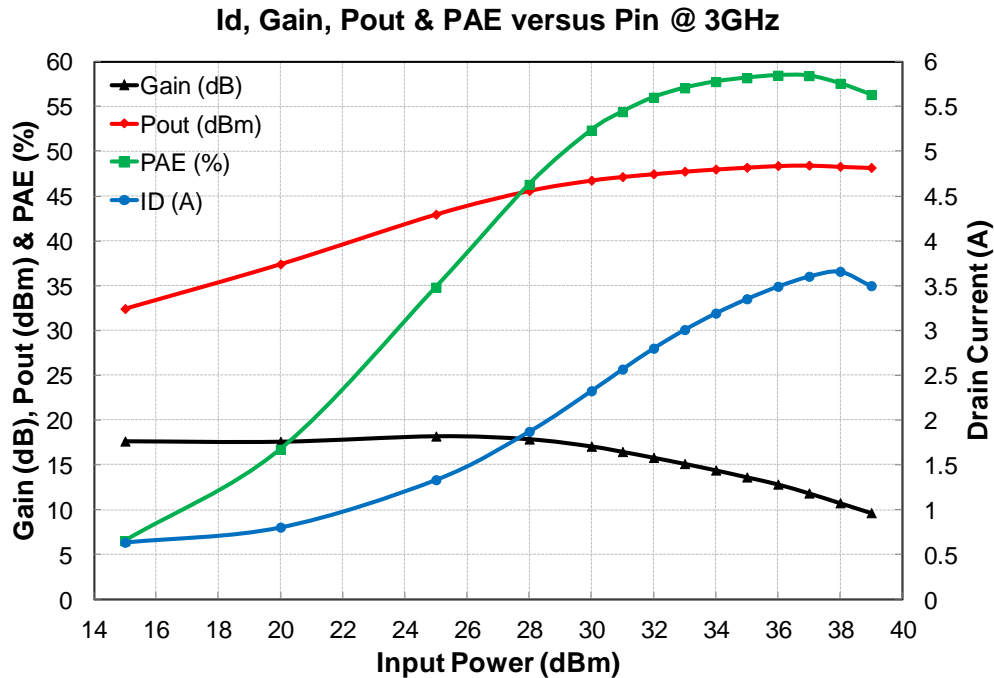


Typical Performance

Power Measurements results at package IN/OUT reference

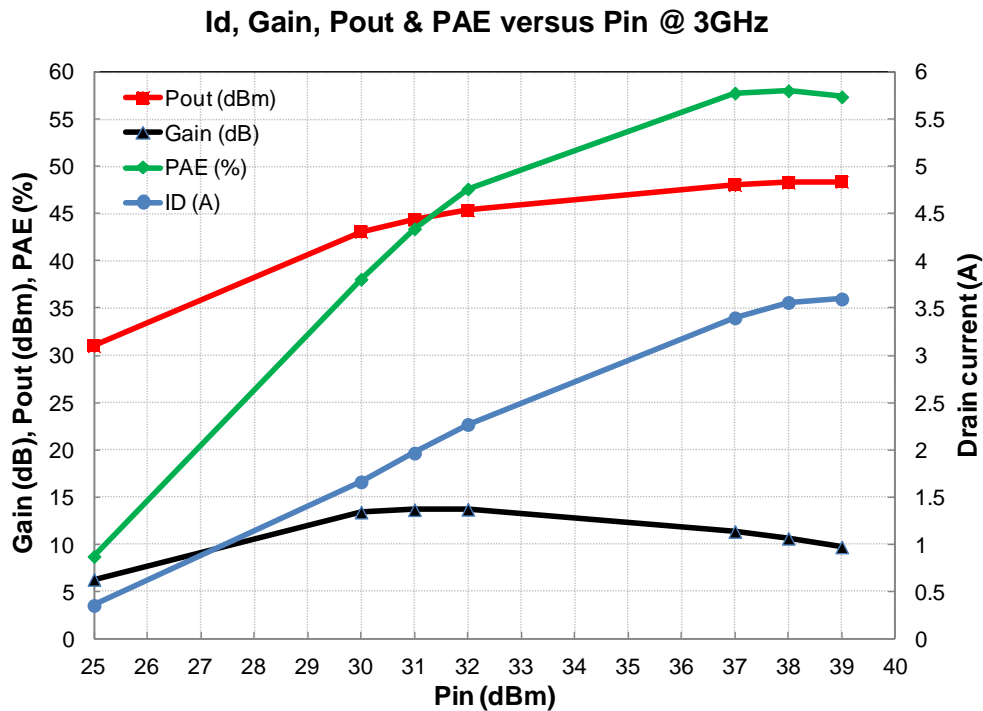
$T_{case} = +25^{\circ}C$, $V_{DS} = +30V$, $I_{D,Q} = 800mA$ (Class AB)

Pulsed input power : 400 μ s / 15%



$T_{case} = +25^{\circ}C$, $V_{DS} = +30V$, $I_{D,Q} = 0mA$ (Class B)

Pulsed input power: 400 μ s / 15%



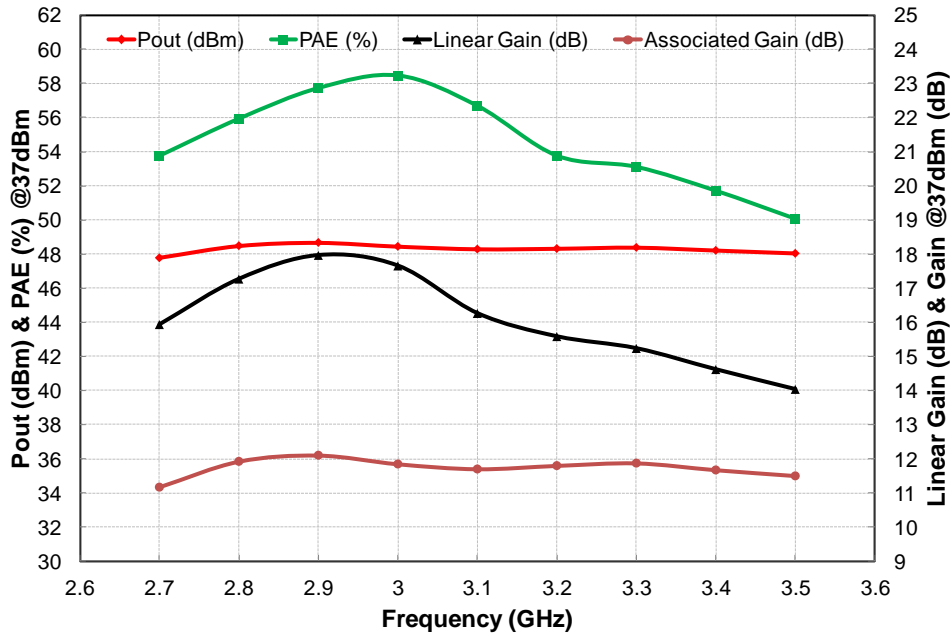
Typical Performance

Power Measurements results at package IN/OUT reference

$T_{case} = +25^{\circ}C$, $V_{DS} = +30V$, $I_{D,Q} = 800mA$ (Class AB)

Pulsed input power : 400 μ s / 15%

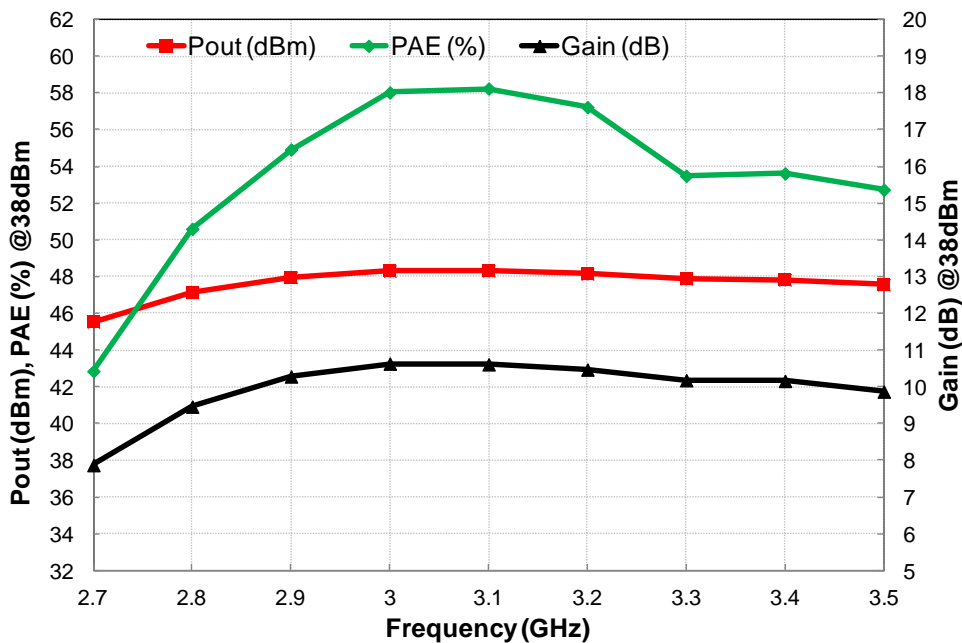
Linear Gain, Associated Gain, Pout & PAE versus Frequency @ Pin=37dBm



$T_{case} = +25^{\circ}C$, $V_{DS} = +30V$, $I_{D,Q} = 0mA$ (Class B)

Pulsed input power : 400 μ s / 15%

Power Gain, Pout & PAE versus Frequency @ Pin=38dBm



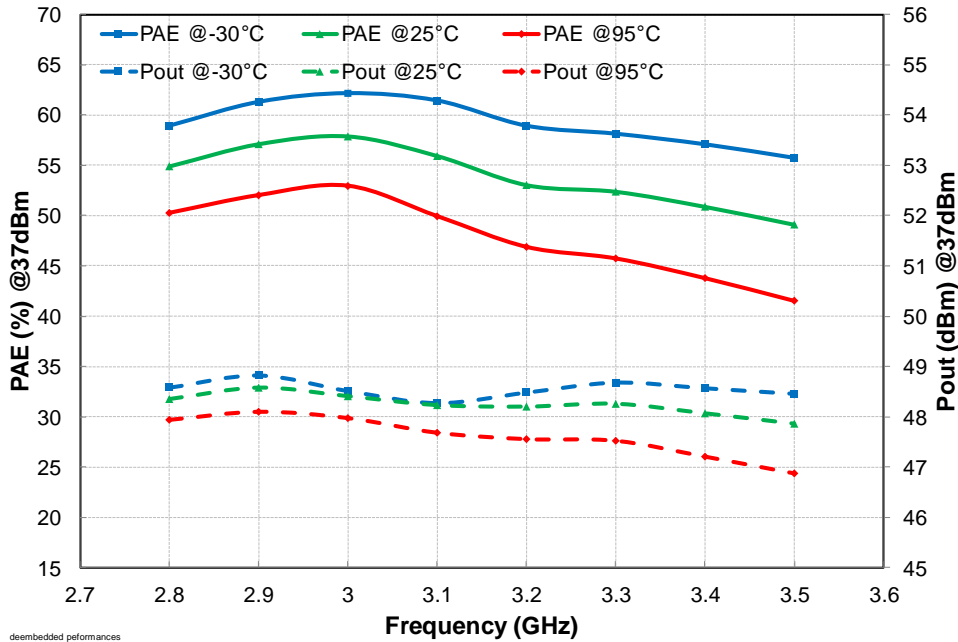
Typical Performance in Temperature

Power Measurements results at package IN/OUT reference

$T_{case} = -30^{\circ}C, +25^{\circ}C, +95^{\circ}C, V_{DS}=30V, V_{GS}=constant (I_{D_Q}=800mA @ 25^{\circ}C - Class AB)$

Pulsed input power : 400 μ s / 15%

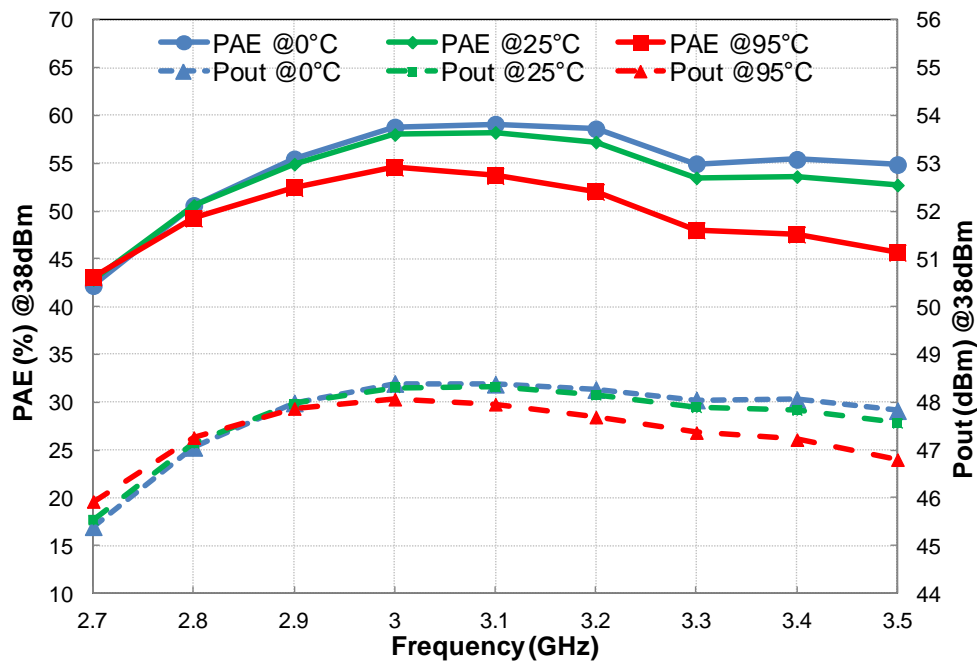
Pout & PAE versus Frequency and Temperature @ Pin=37dBm



$T_{case} = 0^{\circ}C, +25^{\circ}C, +95^{\circ}C, V_{DS}=30V, V_{GS}=constant (I_{D_Q}=0mA @ 25^{\circ}C - Class B)$

Pulsed input power : 400 μ s / 15%

Pout & PAE versus Frequency and Temperature @ Pin=38dBm



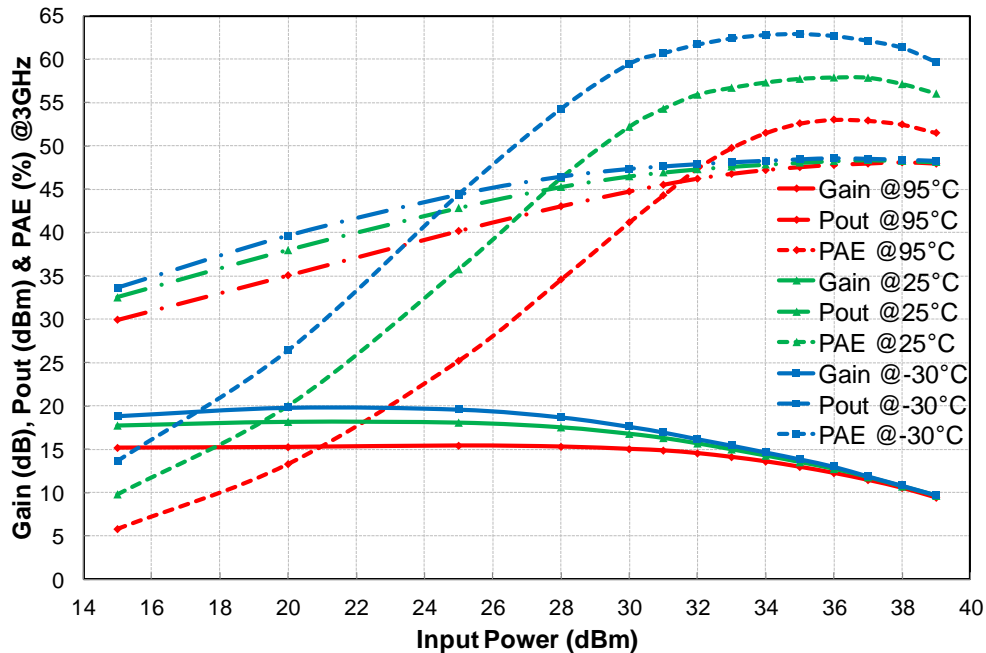
Typical Performance in Temperature

Power Measurements results at package IN/OUT reference

$T_{case} = -30^{\circ}C, +25^{\circ}C, +95^{\circ}C, V_{DS}=30V, V_{GS}=constant (I_{D_Q}=800mA @ 25^{\circ}C - Class AB)$

Pulsed input power : 400µs / 15%

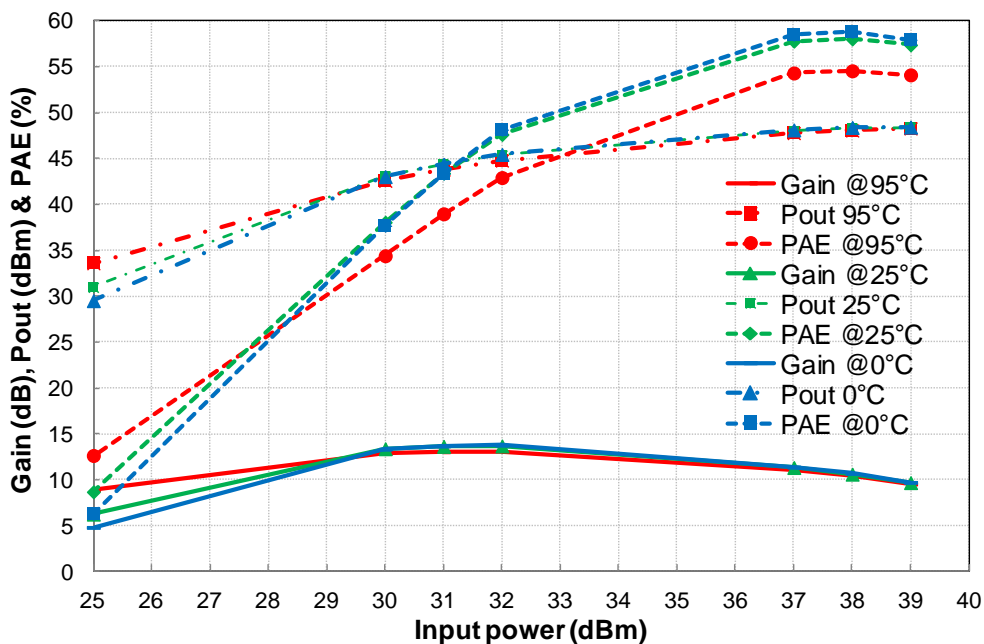
Gain, Pout & PAE versus Pin and Temperature @ 3GHz



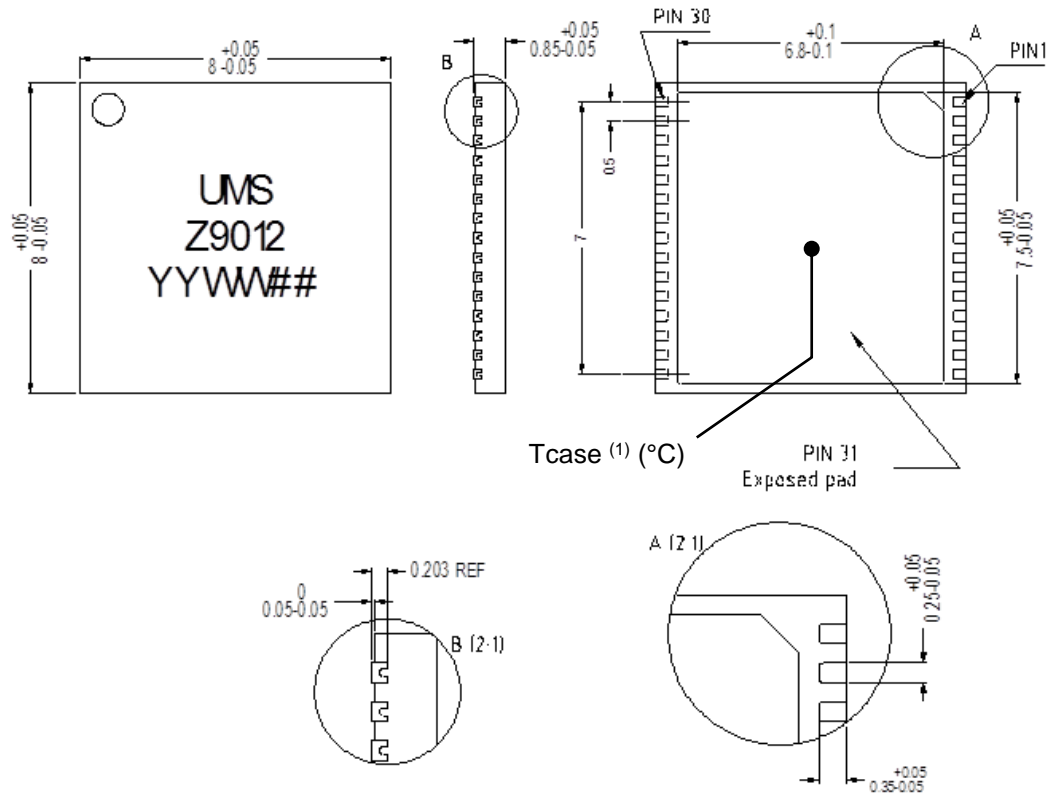
$T_{case} = 0^{\circ}C, +25^{\circ}C, +95^{\circ}C, V_{DS}=30V, V_{GS}=constant (I_{D_Q}=0mA @ 25^{\circ}C - Class B)$

Pulsed input power : 400µs / 15%

Gain, Pout & PAE versus Pin and Temperature @ 3GHz



Package outline

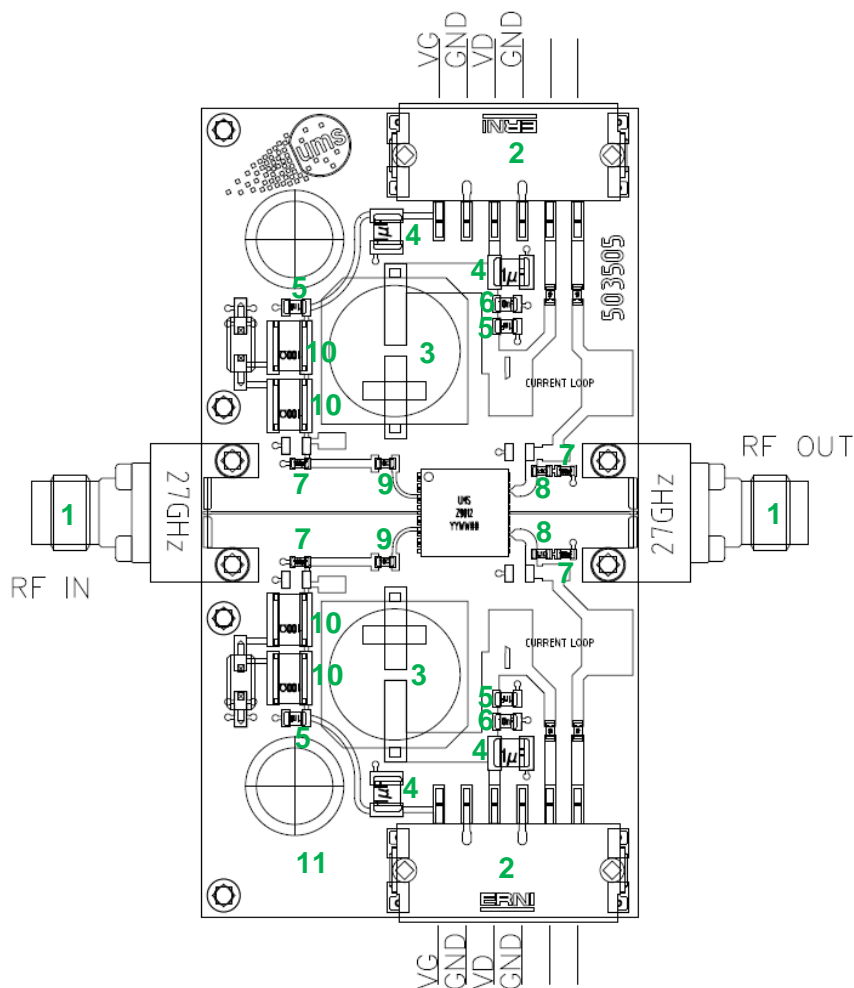


| | | | | | |
|-----------------|----------------------|-----------------------|-----------------------|-----------------------|-----------------------|
| Finish : NiPdAu | 1-NC | 8-RF IN | 15-NC | 22-NC | 29-NC |
| Units : mm | 2-NC | 9-NC | 16-NC | 23-RF OUT | 30-NC |
| | 3-NC | 10-GND ⁽²⁾ | 17-NC | 24-NC | 31-GND ⁽²⁾ |
| | 4-NC | 11-VG | 18-NC | 25-GND ⁽²⁾ | |
| | 5-VG | 12-NC | 19-VD | 26-NC | |
| | 6-GND ⁽²⁾ | 13-NC | 20-NC | 27-VD | |
| | 7-NC | 14-NC | 21-GND ⁽²⁾ | 28-NC | |

⁽¹⁾ Tcase locates the reference point used to monitor the device temperature. This point has been taken at the device / system interface to ease system thermal design.

⁽²⁾ It is strongly recommended to ground all pins marked "GND" through the PCB board. Ensure that the PCB board is designed to provide the best possible ground to the package.

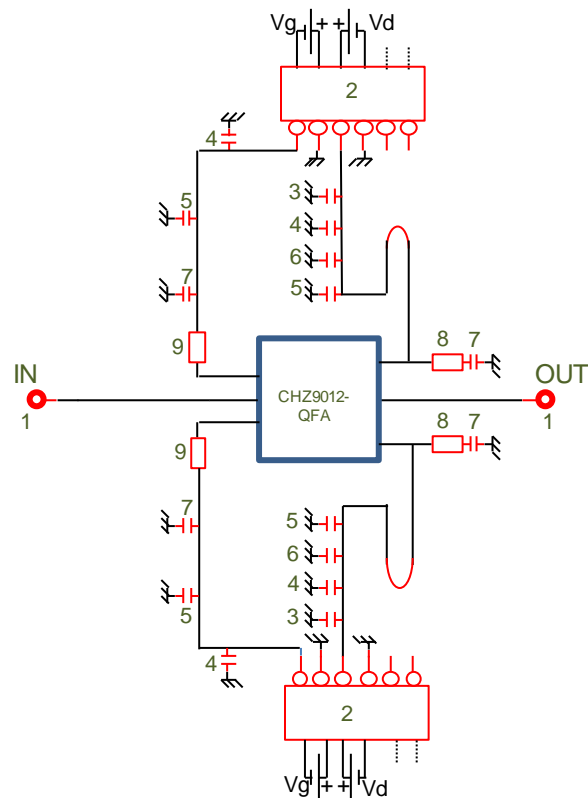
Evaluation board (Ref. 61503234)



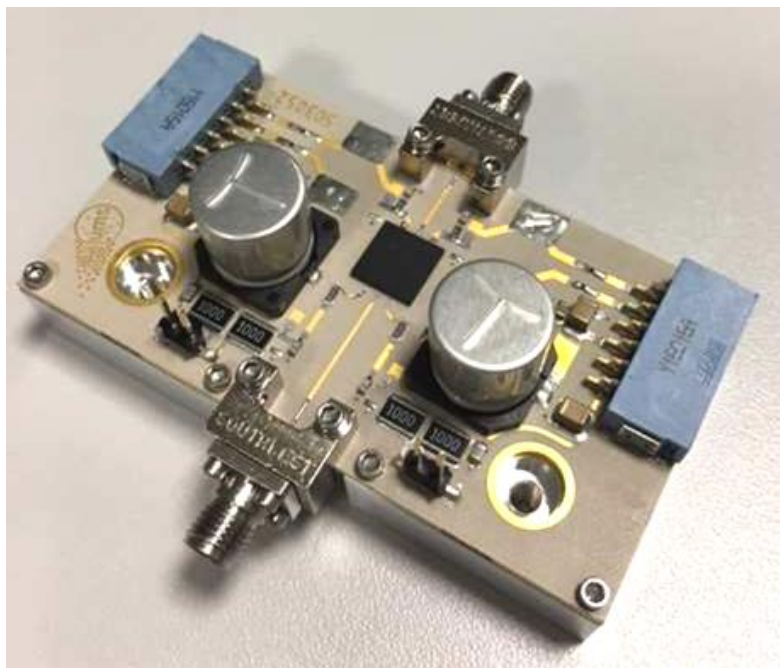
Bill of Materials (Ref. 61503234)

| Designation | Component | Value - Description | Qty |
|-------------|--------------|--|-----|
| 1 | RF Connector | RF-SMA DC-27GHz | 2 |
| 2 | DC Connector | CMS 6cts | 2 |
| 3 | Capacitor | 68 μ F +/-20%. 100V | 2 |
| 4 | Capacitor | 1 μ F +/-10%. 1210 100V | 2 |
| 5 | Capacitor | 1nF +/-5%. 0805 100V | 4 |
| 6 | Capacitor | 10nF +/-10%. 0805 100V | 2 |
| 7 | Capacitor | 100pF +/-5%. 0603 250V | 4 |
| 8 | Resistor | 5.1 Ω +/-1%. 0603 100mW | 2 |
| 9 | Resistor | 10 Ω +/-1%. 0603 0.1W | 4 |
| 10 | Resistor | 100 Ω +/-1%. RCL 1218 1W | 4 |
| 11 | PCB | TACONIC RF35P-0080-CH/Cu1/ Thickness=0.008in (0.203mm)/ Bottom Copper layer: 1mm | 1 |

DC Schematic (Ref. 61503234)



The CHZ9012-QFA does not include any high value decoupling capacitor in the package. Therefore, it is mandatory to provide a good external DC decoupling on the PCB board, as close as possible to the package (See paragraph "Evaluation board").

Demonstration Amplifier Circuit (Ref. 61503234)**ESD sensitivity**

| Standard | Value |
|-------------------|------------------------------|
| JEDEC JESD22-A114 | HBM Class 1A ($\leq 500V$) |
| JEDEC JESD22-A115 | MM Class A ($\leq 100V$) |

Package Information

| Parameter | Value |
|-----------------------|-------------------------------------|
| Package body material | RoHS-compliant |
| | Low stress Injection Molded Plastic |
| Lead finish | NiPdAu |
| MSL Rating | MSL3 (IPC/JEDEC J-STD-020) |

Qualification domain

This part is qualified according to UMS standards including uHAST stress (Accelerated Moisture Resistance-Unbiased HAST) based on JEDEC JESD22-A118.

Recommended package footprint

Refer to the application note AN0017 available at <https://www.ums-rf.com> for package footprint recommendations.

SMD mounting procedure

For the mounting process, standard techniques involving solder paste and a suitable reflow process can be used. For further details, see application note AN0017.

Recommended environmental management

UMS products are compliant with the regulation in particular with the directives RoHS N°2011/65 and REACH N°1907/2006. More environmental data are available in the application note AN0019 also available at <https://www.ums-rf.com>.

Recommended ESD management

Refer to the application note AN0020 available at <https://www.ums-rf.com> for ESD sensitivity and handling recommendations for the UMS package products.

Ordering Information

DFN 8x8 package:

CHZ9012-QFA/XY

Stick: XY = 20

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